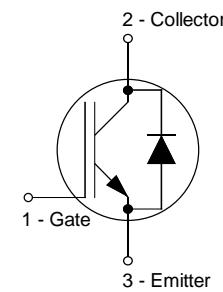
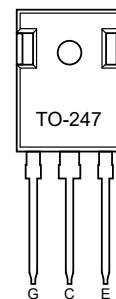


650V 75A Trench and Field Stop IGBT

Product Information

Features	Package Marking and Ordering Information	
◆ Advanced Field Stop technology	◆ Product Name:	KJG75N65P
◆ Low Switching Power Loss	◆ Marking:	KJG75N65P
◆ Low Switching Surge and Noise	◆ Package:	TO-247
◆ Low EMI	◆ Quantity:	300 pcs
◆ T_J 175°C		
Applications		
◆ Industrial UPS		
◆ Welding Machine		
◆ Solar Converters		
◆ Energy Storage		
◆ EV Charger		



Maximum Rated Values ($T_{vj}=25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CES}	650	V
Gate-Emitter Voltage	V_{GE}	± 20	V
Transient Gate-Emitter Voltage ($t_p \leq 10 \mu\text{s}$, $D < 0.01$)		± 30	
DC Collector Current, $T_C=25^\circ\text{C}$ (Limited by T_J max)	I_C	115	A
DC Collector Current, $T_C=100^\circ\text{C}$ (Limited by T_J max)		75	
Pulsed collector current (T_p limited by T_J max) ^[1]	I_{CPuls}	300	
Diode Forward Current, $T_C=25^\circ\text{C}$ (T_p limited by T_J max)	I_F	115	
Diode Forward Current, $T_C=100^\circ\text{C}$ (T_p limited by T_J max)		75	
Turn-Off Safe Operating Area $V_{CE} \leq 650 \text{ V}$, $T_{vj} \leq 175^\circ\text{C}$, $t_p = 1 \mu\text{s}$	-	300	
IGBT Max. Power Dissipation	P_{D_IGBT}	420	
FWD Max. Power Dissipation	P_{D_FRD}	375	
Operating Junction Temperature	T_{vj}	-40 to 175	
Storage Temperature	T_{stg}	-55 to 175	°C

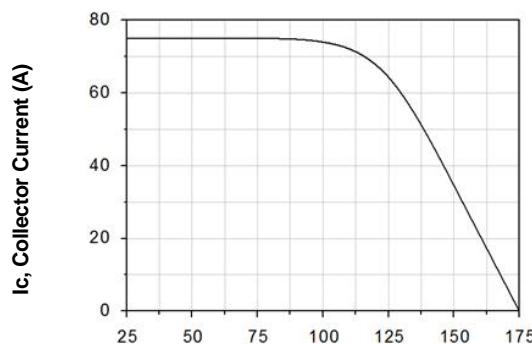
Thermal Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-Ambient	R_{thJA}	-	-	50	°C/W
IGBT Thermal Resistance, Junction-Case	R_{thJC}	-	-	0.35	
Diode Thermal Resistance, Junction-Case	R_{thJCD}	-	-	0.4	

Electrical Characteristics (T_{VJ}=25°C, unless otherwise specified)

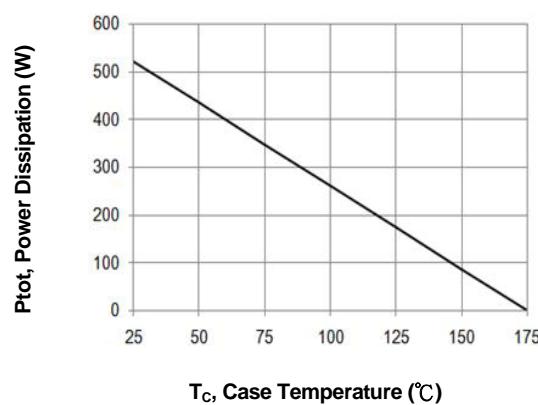
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Static Characteristics						
Collector-Emitter Breakdown Voltage	V _{(BR)CES}	V _{GE} =0 V, I _C =0.50 mA	650	-	-	V
C-E Leakage Current	I _{CES}	V _{CE} =650 V, V _{GE} =0 V	-	-	200	µA
G-E Leakage Current	I _{GES}	V _{CE} =0 V, V _{GE} =±20 V	-	-	±200	nA
G-E Threshold Voltage	V _{GE(th)}	I _C =250 µA, V _{CE} =V _{GE}	5.0	5.8	6.6	V
Collector-Emitter Saturation Voltage	V _{CE(sat)}	V _{GE} =15 V, I _C =75 A				V
		T _{VJ} =25°C	-	1.80	2.25	
		T _{VJ} =175°C	-	2.50	-	
Diode Forward Voltage	V _F	V _{GE} =0 V, I _F =75 A				
		T _{VJ} =25°C	-	1.5	3.0	
		T _{VJ} =175°C	-	1.3	-	
Dynamic Characteristics						
Input Capacitance	C _{ies}	V _{CE} =25 V, V _{GE} =0 V, f=1 MHz	-	9600	-	pF
Output Capacitance	C _{oes}		-	310	-	
Reverse Transfer Capacitance	C _{res}		-	100	-	
Gate Charge	Q _G	V _{CC} =520 V, I _C =75 A, V _{GE} =15 V	-	330	-	nC
IGBT Switching Characteristics						
Turn-on Delay Time	t _{d(on)}	T _j =25°C, V _{CC} =400 V, I _C =75 A, V _{GE} =15 V, R _G =10 Ω, Inductive load	-	80	-	ns
Rise Time	t _r		-	33	-	
Turn-off Delay Time	t _{d(off)}		-	150	-	
Fall Time	t _f		-	85	-	
Turn-on Energy	E _{on}		-	1.25	-	
Turn-off Energy	E _{off}		-	0.97	-	
Total Switching Energy	E _{ts}		-	2.22	-	
Turn-on Delay Time	t _{d(on)}	T _j =175°C, V _{CC} =400 V, I _C =75 A, V _{GE} =15 V, R _G =10 Ω, Inductive load	-	74	-	ns
Rise Time	t _r		-	34	-	
Turn-off Delay Time	t _{d(off)}		-	160	-	
Fall Time	t _f		-	110	-	
Turn-on Energy	E _{on}		-	1.60	-	
Turn-off Energy	E _{off}		-	1.30	-	
Total Switching Energy	E _{ts}		-	2.90	-	
Diode Characteristics						
Diode Reverse Recovery Time	t _{rr}	T _j =25°C, V _R =400 V, I _F =75 A, dI _F /dt=500 A/µs	-	107	-	ns
Diode Reverse Recovery Charge	Q _{rr}		-	1.1	-	µC
Diode Peak Reverse Recovery Current	I _{rrm}		-	17.1	-	A
Diode Reverse Recovery Time	t _{rr}	T _j =175°C, V _R =400 V, I _F =75 A, dI _F /dt=500 A/µs	-	194	-	ns
Diode Reverse Recovery Charge	Q _{rr}		-	5.2	-	µC
Diode Peak Reverse Recovery Current	I _{rrm}		-	49.3	-	A

Typical Electrical and Thermal Characteristics



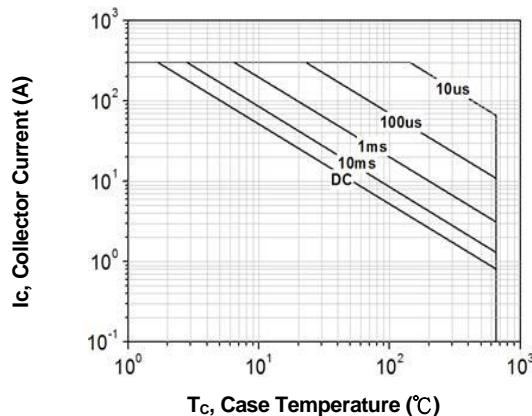
V_{CE} , Collector to Emitter Voltage (V)

Figure 1. Collector current vs. case temperature ($V_{GE} \leqslant 15V$, $T_{vj} \leqslant 175^{\circ}C$)



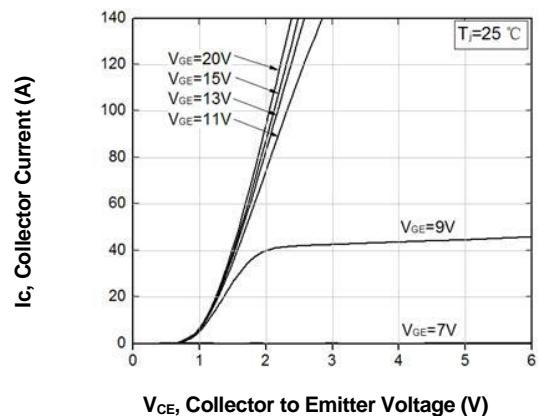
T_c , Case Temperature (°C)

Figure 2. Power dissipation vs. case temperature ($T_{vj} \leqslant 175^{\circ}C$)



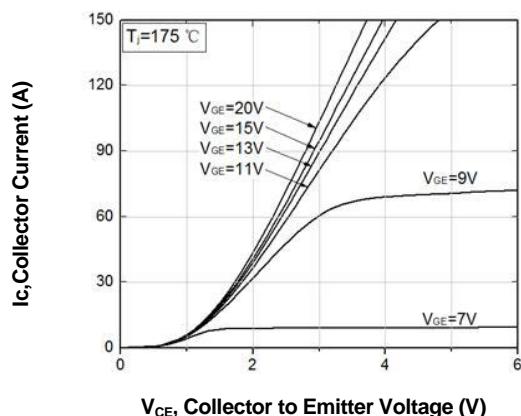
T_c , Case Temperature (°C)

Figure 3. Forward bias safe operating area ($D=0$, $T_c=25^{\circ}C$, $T_{vj} \leqslant 175^{\circ}C$; $V_{GE}=15V$)



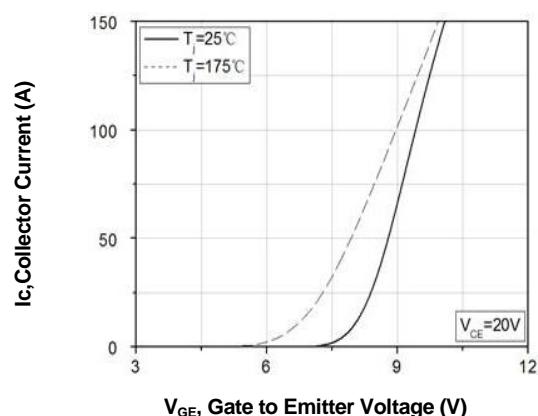
V_{CE} , Collector to Emitter Voltage (V)

Figure 4. Typical output characteristic ($T_{vj}=25^{\circ}C$)



V_{CE} , Collector to Emitter Voltage (V)

Figure 5. Typical output characteristic ($T_{vj}=175^{\circ}C$)



V_{GE} , Gate to Emitter Voltage (V)

Figure 6. Typical transfer characteristic ($V_{CE}=20V$)

Typical Electrical and Thermal Characteristics (cont.)

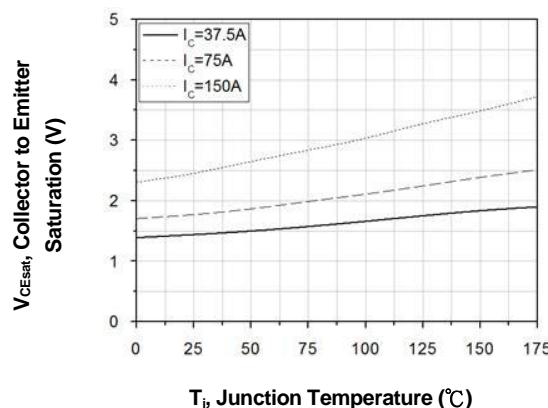


Figure 7. Typical collector-emitter saturation voltage vs. T_{vj} ($V_{GE}=20V$)

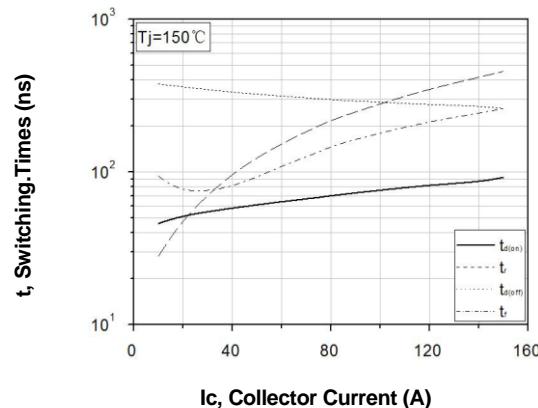


Figure 8. Typical switching times vs. collector current (Ind. load, $T_{vj}=150\text{ }^{\circ}\text{C}$, $V_{CE}=400V$, $V_{GE}=15/0V$, $R_g=12\Omega$)

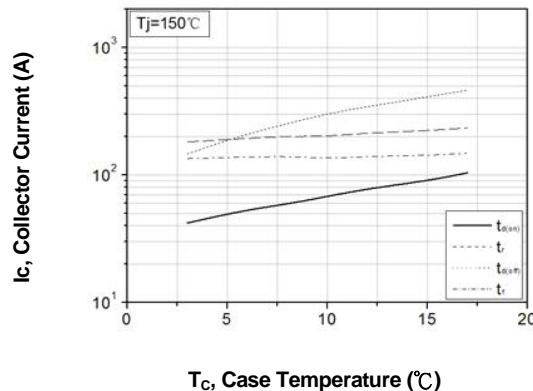


Figure 9. Typical switching times vs. gate resistor (Ind. Load, $T_{vj}=150\text{ }^{\circ}\text{C}$, $V_{CE}=400V$, $V_{GE}=15/0V$, $I_c=75A$)

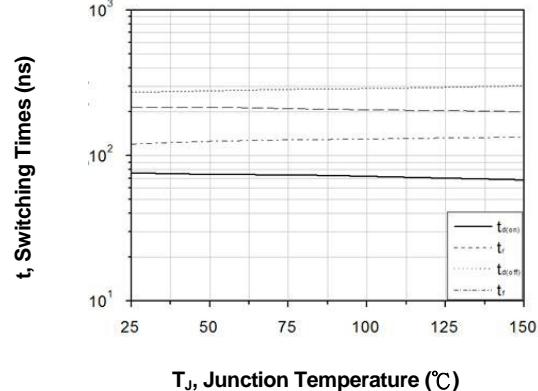


Figure 10. Typical switching times vs. T_{vj} (Ind. Load, $V_{CE}=400V$, $V_{GE}=15/0V$, $I_c=75A$, $R_g=10\Omega$)

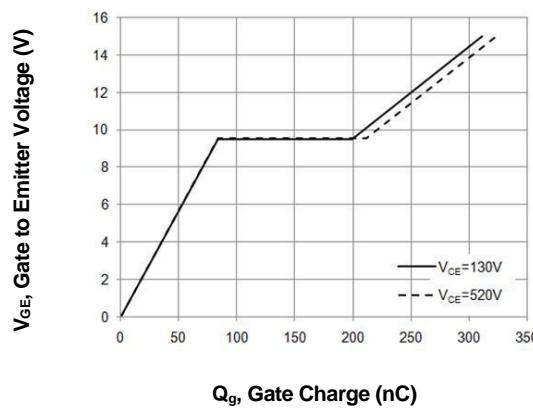


Figure 11. Typical gate charge ($I_c=75A$)

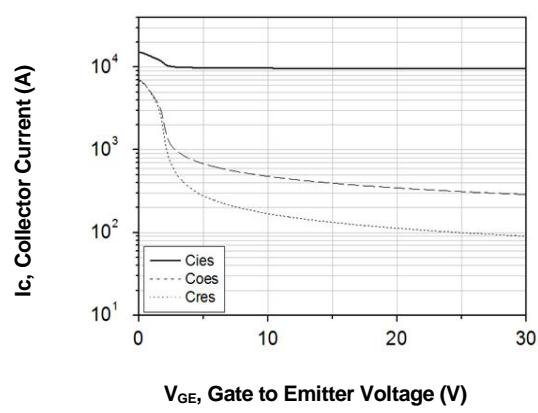
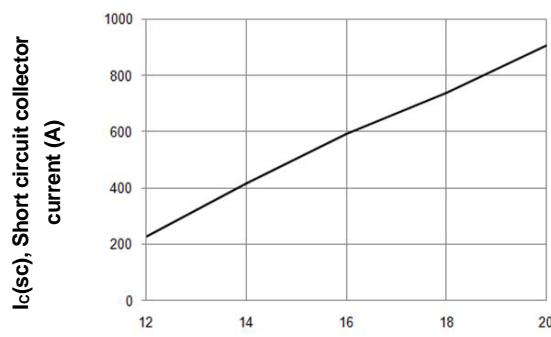


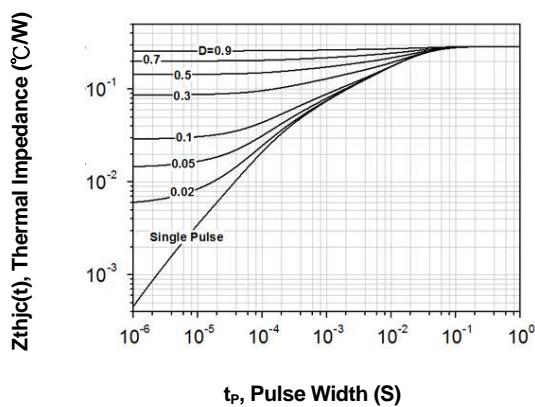
Figure 12. Typical capacitance vs. collector-emitter voltage ($V_{GE}=0V$, f=1MHz)

Typical Electrical and Thermal Characteristics (cont.)



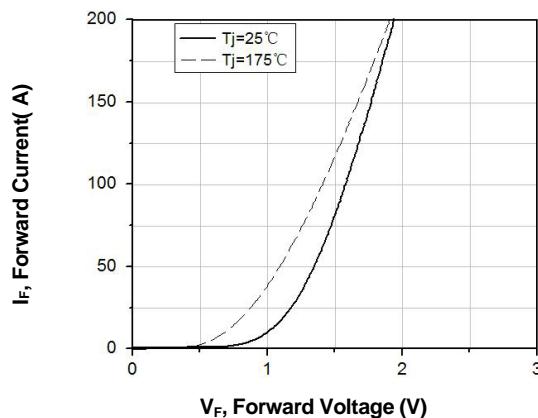
V_{GE}, Gate to Emitter Voltage (V)

Figure 13. Typical short circuit collector current vs. gate-emitter voltage
($V_{CE} \leq 400V$ start at $T_{vj}=25^{\circ}\text{C}$)



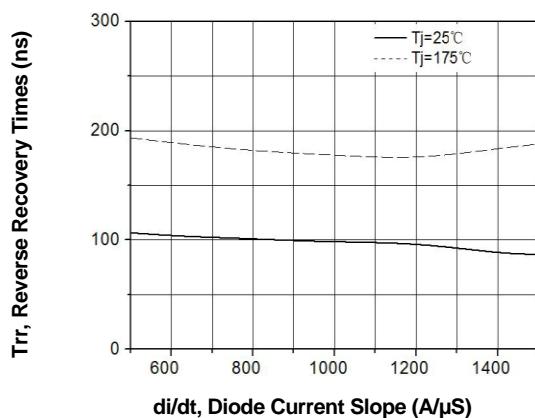
t_p, Pulse Width (S)

Figure 14. IGBT transient thermal impedance
($D=t_p/T$)



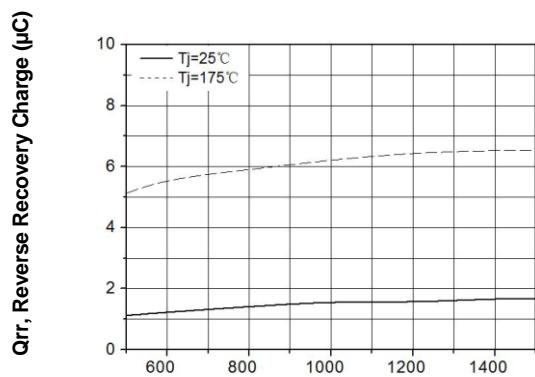
V_F, Forward Voltage (V)

Figure 15. Typical diode forward current vs. forward voltage



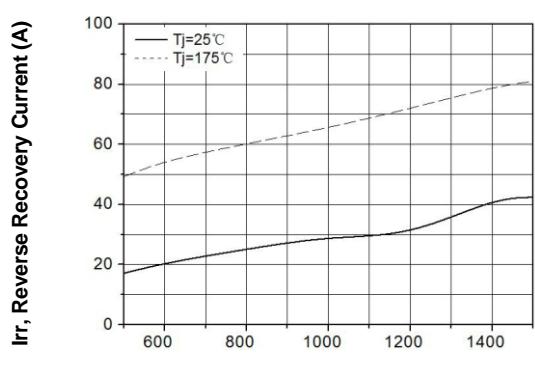
di/dt, Diode Current Slope (A/μS)

Figure 16. Typical reverse recovery time vs. diode current slope
($V_R=400V$)



di/dt, Diode Current Slope (A/μS)

Figure 17. Typical reverse recovery charge vs. diode current slope
($V_R=400V$)

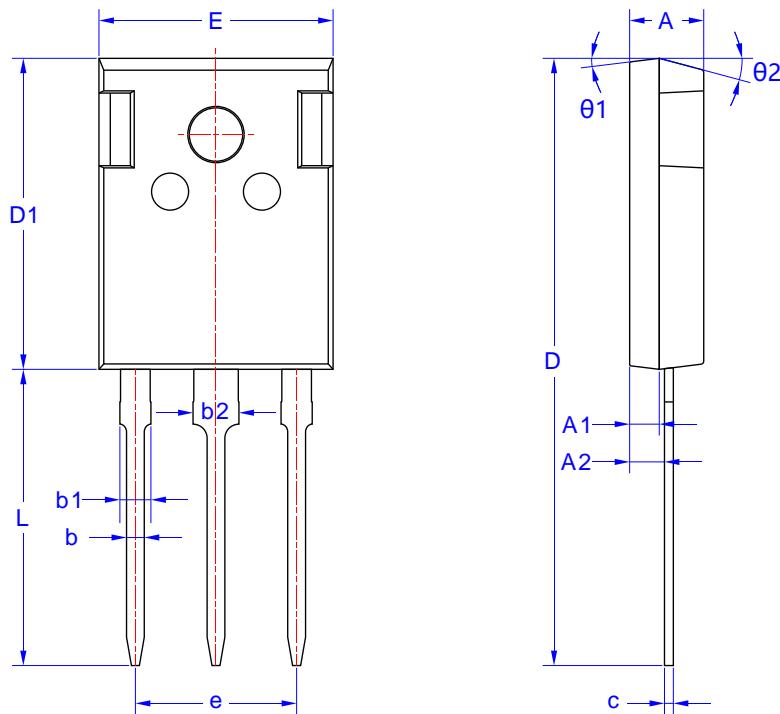


di/dt, Diode Current Slope (A/μS)

Figure 18. Typical reverse recovery current vs. diode current slope
($V_R=400V$)

Package Mechanical Data

TO-247 Package



Symbol	Dimensions in Millimeters		
	MIN.	NOM.	MAX.
A	4.90	5.00	5.10
A1	1.90	2.00	2.10
A2	2.25	2.35	2.45
b		1.20	
b1		2.10	
b2		3.10	
c		0.60	
D	40.00	41.00	42.00
D1	20.80	21.00	21.20
E	15.60	15.80	16.00
e		10.88	
L	19.80	20.00	20.20
θ1		7°	
θ2		15°	